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WHAT IS CLAIMED IS:

1. A method for synthesizing a compound having the formula E(GeH₃)₃ wherein E is selected from the group consisting of arsenic (As), antimony (Sb) and phosphorus (P), the method comprising combining GeH₃Br with [(CH₃)₃Si]₃E under conditions whereby E(GeH₃)₃ is obtained.

- 2. The method of claim 1 further comprising purifying the obtained E(GeH₃)₃.
- 3. The method of claim 1 wherein the step of purifying the obtained E(GeH₃)₃ comprises trap-to-trap fractionation.
- 4. The method of claim 1 wherein E(GeH₃)₃ is obtained with a yield from about 70% to about 76%.
- 5. A method for synthesizing a compound having the formula E(GeH₃)₃ wherein E is selected from the group consisting of arsenic (As), antimony (Sb) and phosphorus (P), the method comprising combining GeH₃Br with [(CH₃)₃Si]₃E to obtain E(GeH₃)₃ according to the formula:

$$3 \text{ GeH}_3\text{Br} + [(CH_3)_3\text{Si}]_3\text{E} \rightarrow 3 (CH_3)_3\text{Si Br} + (GeH_3)_3\text{E}$$

- 6. The method of claim 5 further comprising purifying the obtained E(GeH₃)₃.
- 7. The method of claim 5 wherein the step of purifying the obtained E(GeH₃)₃ comprises trap-to-trap fractionation.
- 8. The method of claim 5 wherein E(GeH₃)₃ is obtained with a yield from about 70% to about 76%.
- 9. A method for doping a region of a semiconductor material in a chemical vapor deposition reaction chamber, the method comprising introducing into the chamber a gaseous precursor having the formula E(GeH₃)₃, wherein E is selected from the group consisting of arsenic (As), antimony (Sb) and phosphorus (P).
- 10. The method of claim 9 wherein the semiconductor material comprises silicon (Si).
- 11. The method of claim 9 wherein the semiconductor material comprises germanium (Ge).

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12. The method of claim 9 wherein the semiconductor material comprises SiGeSn.

- 13. The method of claim 9 wherein the semiconductor material comprises SnGe.
- 14. A method for depositing a doped epitaxial Ge-Sn layer on a substrate in a chemical vapor deposition reaction chamber, the method comprising:

introducing into the chamber a gaseous precursor comprising SnD₄ mixed in H₂ under conditions whereby the epitaxial Ge-Sn layer is formed on the substrate; and

introducing into the chamber a gaseous precursor having the formula E(GeH₃)₃, wherein E is selected from the group consisting of arsenic (As), antimony (Sb) and phosphorus (P).

- 15. The method of claim 14 wherein the gaseous precursor is introduced at a temperature in a range of about 250°C to about 350°C.
- 16. The method of claim 14 wherein the substrate comprises silicon.
- 17. The method of claim 14 wherein the silicon comprises Si(100).
- 18. The method of claim 14 wherein the Ge-Sn layer comprises Sn_xGe_{1-x} and x is in a range from about .02 to about .20.
- 19. A method for forming a Group IV semiconductor film, the method comprising forming the Group IV semiconductor by a chemical vapor deposition method, said Group IV semiconductor film being doped with impurities at a concentration ranging from about 10²¹ atoms/cm³ to about several percent, the impurities being selected from the group consisting of arsenic (As), phosporous (P) and antimony (Sb).
- 20. A method for forming a Group IV semiconductor film, the method comprising: forming the Group IV semiconductor film by a chemical vapor deposition method; and

while forming the Group IV semiconductor film, doping the film with impurities at a concentration ranging from about 10²¹ atoms/cm³ to about 3 at. %, the impurities being selected from the group consisting of arsenic (As), antimony (Sb) and phosphorus (P)

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21. The method for forming a Group IV semiconductor film according to claim 20, wherein t arsenic (As), antimony (Sb) and phosphorus (P) are added to the Group IV semiconductor film by diffusion methods.

- 22. The method for forming a Group IV semiconductor film according to claim 20, wherein said doping step comprises introducing the As, P, or Sb impurities into a reaction chamber as hydride compounds, together with at least SnD₄, GeH₄, Ge₂H₆.
- 23. A method of preparing (E)H_x (GeH₃)_{3-x}, where x= 1 or 2 and E is selected from the group consisting of P, As, Sb, the method comprising reacting inorganic or orhanometallic compounds of the E element with an alkali germyl or a halogenated germane.
- 24. The method of preparing (E)H_x (GeH₃)_{3-x} according to claim 23 wherein the alkali germyl comprises KGeH₃.
- 25. The method of preparing (E)H_x (GeH₃)_{3-x} according to claim 23 wherein the halogenated germane comprises BrGeH₃.